



High Voltage Trench Schottky Diode

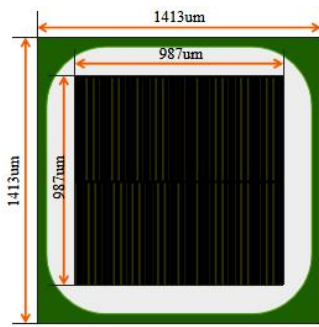
FEATURES

- Trench MOS Schottky technology
- Die in 6" Wafer Form
- 120V, 3A*
- $V_F=0.67V$ (typ.)**

Electrical Characteristics (T_j=25°C)

Parameter	Description	Min.	Typ.	Max.	Unit	Test Condition
V _{RRM}	Maximum repetitive peak reverse voltage	125	137	—	V	I _R =500μA
V _F	Static Forward Voltage	—	0.48	0.53	V	I _F =1A
		—	0.58	0.64	V	I _F =2A
		—	0.67	0.73	V	I _F =3A
I _R ***	Cathode-To-Anode Leakage Current	—	4	30	μA	V _R =120V
T _J , T _{STG}	Operating and Storage Temperature Range	-55°C to 150°C Max				
*** Pulse width < 300 uS, Duty cycle < 2%						

Mechanical Data

Die Size	1473×1473	μm ²	CHIP DRAWING (Scribe Line is Excluded)
Source Pad Size	987×987	μm ²	
Scribe Line Size	60	μm	
Wafer Diameter	6	in	
Wafer Thickness	250	μm	
Estimated Gross Die	7321 (Yield>98%)		
Anode Metal Thickness	Al\Ti\Ni\Ag(2.8um\0.1um\0.2um\1.8um)		
Cathode Metal Thickness	Ti,\Ni\ Ag(0.2um\0.3um\2um)		
Recommended Storage Environment	Store in original container, in dry nitrogen, < 6 months at an ambient temperature of 23℃±3℃ >		

* Electrical characteristics are reported for the reference packaged part (TO-220) and can not be guaranteed in die sales form.

** Electrical characteristics are reported for the bare die. Variations in customer packaging materials, dimensions and processes may affect parametric performance.